

LC898262XHTBG

PIN DESCRIPTION

Table 1. PIN DESCRIPTION

Symbol	Description
I	Input
O	Output
P	Power supply, GND
NC	Not connect
B	Bidirection

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**Process When Pins Are Not Used*

onsemi

LC898262XHTBG

BLOCK DIAGRAM

*Consider

LC898262XHTBG

ELECTRICAL CHARACTERISTICS

Table 2. ABSOLUTE MAXIMUM RATINGS (VSS = 0 V)

Symbol	Parameter	Condition	Rating	Unit
V _{I1} max, V _{O1} max	Input/Output Voltage (SCL, SDA)	T _a ≤ 25°C	-0.3 to V _{DD} + 0.3	V
V _{IO} max	Supply Voltage (IOVDD)	T _a ≤ 25°C	-0.3 to 4.6	V
V _{I2} max, V _{O2} max	Input/Output Voltage (SSB, SCLK, SDIO)	T _a ≤ 25°C	-0.3 to V _{IO} + 0.3	V
T _{stg}	Storage Ambient Temperature		-55 to +125	°C
T _{opr}	Operating Ambient Temperature		-30 to +70	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. RECOMMENDED OPERATING CONDITIONS (T_A = -30 to +70°C, VSS = 0 V)

Symbol	Parameter
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Min33 0 TD08bol464ymbol

LC898262XHTBG

AC Specification of TWIF

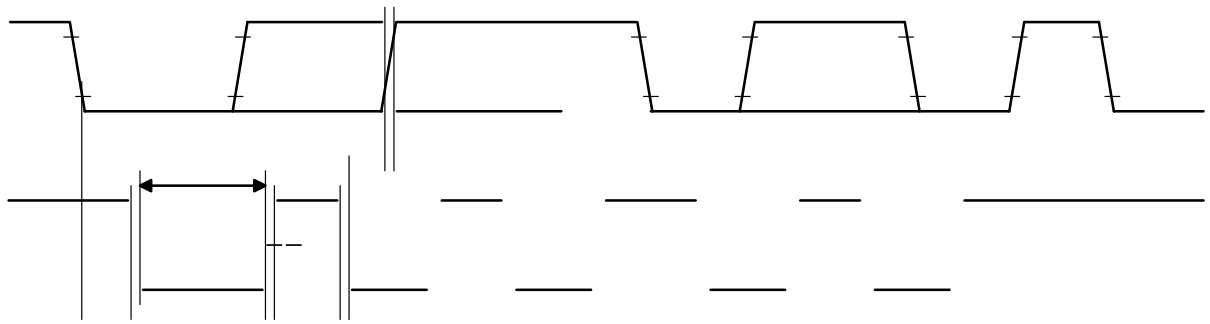


Figure 5.2 wire Serial Interface Timing Definition

LC898262XHTBG

AC Specification of Digital Gyro I/F (Master)

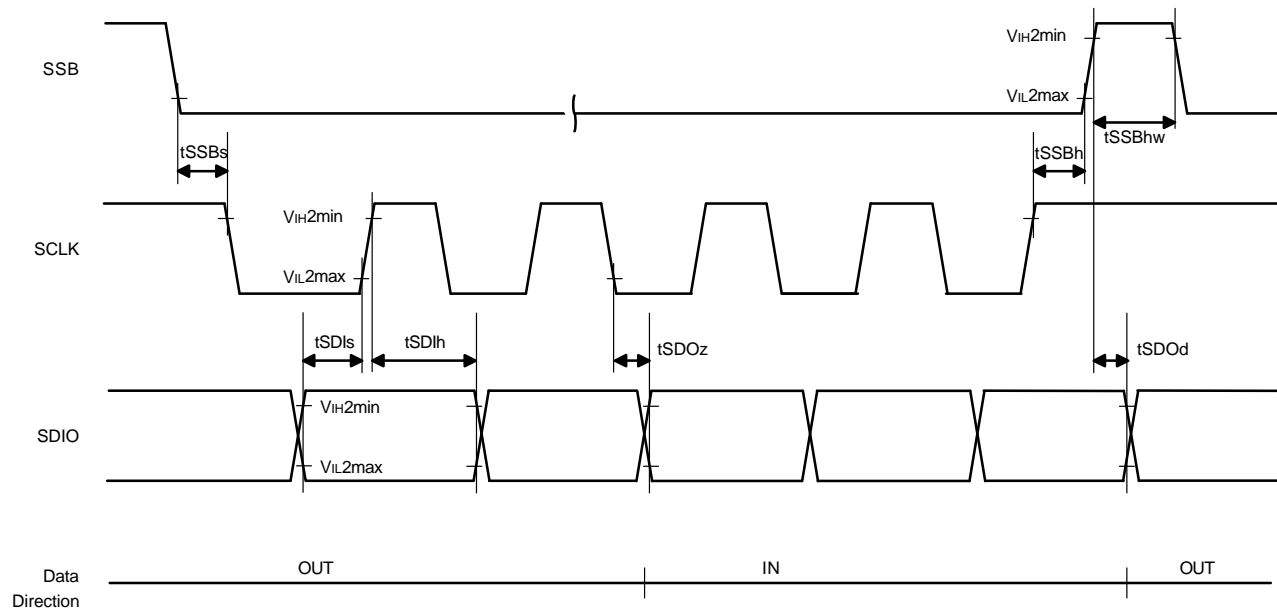


Figure 6. Digital Gyro interface (Master) Timing Definition

LC898262XHTBG

AC Specification of Digital Gyro I/F (Slave)

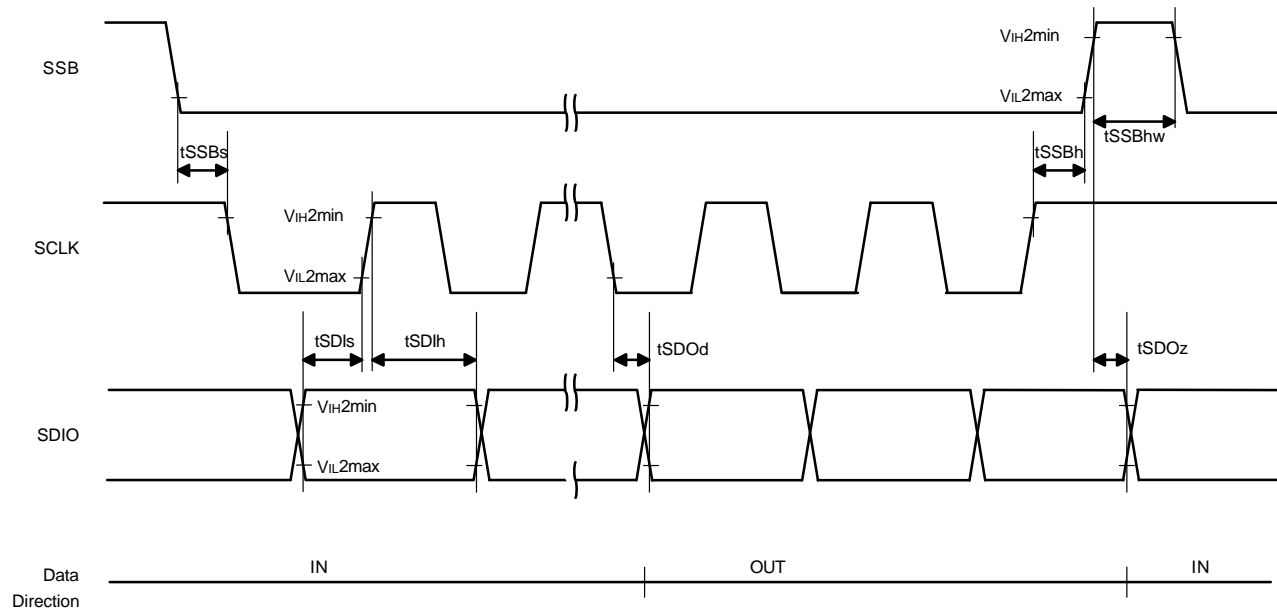


Figure 7. Digital Gyro Interface (Slave) Timing Definition

LC898262XHTBG

ORDERING INFORMATION

Device	Package Type	Shipping [†]
LC898262XHTBG	WLCSP10 0.77x2.27x0.33 (Pb-Free)	4000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

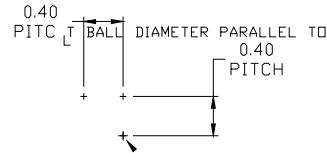
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP10 0.77x2.27x0.33
 CASE 567YK
 ISSUE A

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A		0.33	0.35
A1	0.034	0.040	0.046
A2	0.2525	0.265	0.2775
A3	0.025 REF		
b	0.15	0.17	0.19
D	0.720	0.770	0.820
E			
e	0.40 BSC		



BOTTOM V

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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